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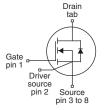
Vishay Siliconix

HALOGEN

FREE

EF Series Power MOSFET With Fast Body Diode

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N-Channel MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	65	50			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.050			
Q _g max. (nC)	9	0			
Q _{gs} (nC)	2	6			
Q _{gd} (nC)	1	4			
Configuration	Sin	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SiHK055N60EF-T1GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	I _D	40	A	
	VGS at 10 V	T _C = 100 °C		26		
Pulsed drain current ^a			I _{DM}	110		
Linear derating factor				1.89	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P_{D}	236	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	- V/ns		
Reverse diode dv/dt ^d			50			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJA}	=	50 ^c	°C/W		
Maximum junction-to-case (drain)	R _{thJC}	-	0.53	C/VV		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static				L			
Drain-source breakdown voltage	V _{DS}	V _{GS} =	600	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.55	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	5.0	V
Cata aguraa laakaga		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	V _{GS} = ± 30 V		-	± 1	μΑ
Zeve gete veltege dvein euwent	1	V _{DS} =	480 V, V _{GS} = 0 V	-	-	1	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 16 A	-	0.050	0.058	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 10 V, I _D = 16 A	-	22	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	3667	-	pF
Output capacitance	C _{oss}	,	$V_{DS} = 0 V_{r}$, $V_{DS} = 100 V_{r}$		143	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	5	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	146	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	749	-	
Total gate charge	Qg			-	60	90	
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$	$V_{GS} = 10 \text{ V}$ $I_D = 16 \text{ A}, V_{DS} = 480 \text{ V}$		26	-	nC
Gate-drain charge	Q_gd				14	-	
Turn-on delay time	t _{d(on)}			-	35	70	
Rise time	t _r	V _{DD} =	$V_{DD} = 480 \text{ V}, I_D = 16 \text{ A}, V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		40	80	no
Turn-off delay time	t _{d(off)}	V _{GS} =			56	84	ns
Fall time	t _f			-	29	58	
Gate input resistance	R_g	f = 1 MHz		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	es						
Continuous source-drain diode current	I _S	showing the	MOSFET symbol showing the		-	40	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	110	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 16 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	-			126	252	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}$, $I_F = I_S = 16 \text{A}$, $di/dt = 100 \text{A/}\mu\text{s}$, $V_R = 400 \text{V}$		-	0.8	1.6	μC
Reverse recovery current	I _{RRM}			_	14	-	Α

Notes

- e. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V
- f. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V
- g. When mounted on 1" x 1" FR4 board



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

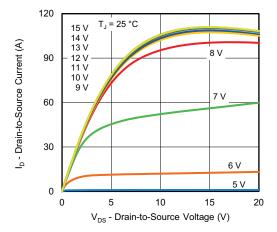


Fig. 1 - Typical Output Characteristics

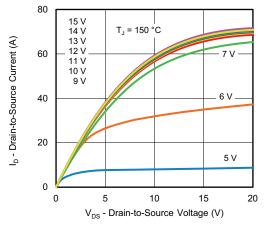


Fig. 2 - Typical Output Characteristics

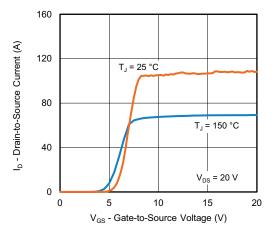


Fig. 3 - Typical Transfer Characteristics

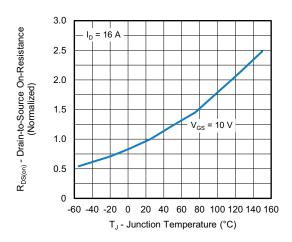


Fig. 4 - Normalized On-Resistance vs. Temperature

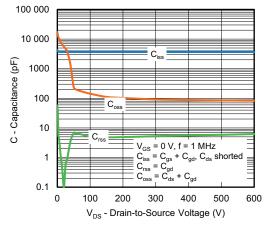


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

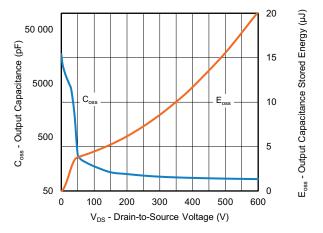


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



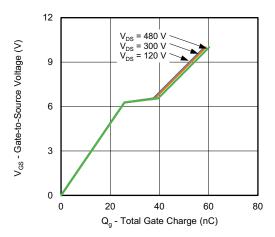


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

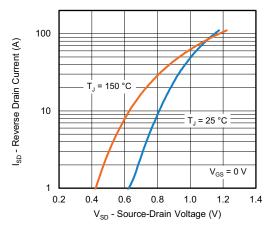


Fig. 8 - Typical Source-Drain Diode Forward Voltage

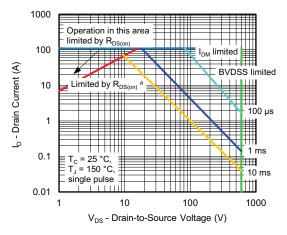


Fig. 9 - Maximum Safe Operating Area



h. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

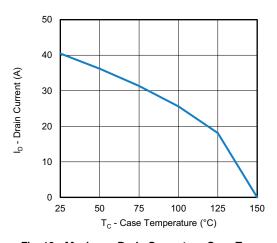


Fig. 10 - Maximum Drain Current vs. Case Temperature

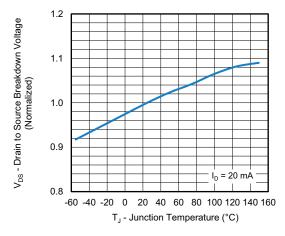


Fig. 11 - Temperature vs. Drain-to-Source Voltage



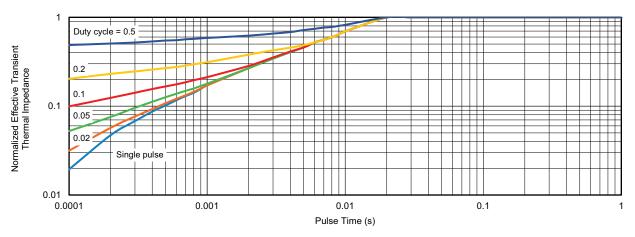


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

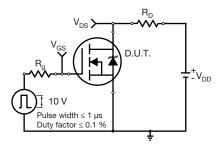


Fig. 13 - Switching Time Test Circuit

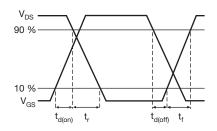


Fig. 14 - Switching Time Waveforms

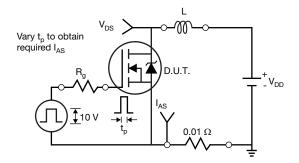


Fig. 15 - Unclamped Inductive Test Circuit

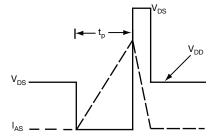


Fig. 16 - Unclamped Inductive Waveforms

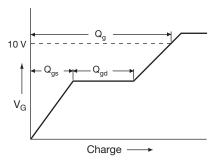


Fig. 17 - Basic Gate Charge Waveform

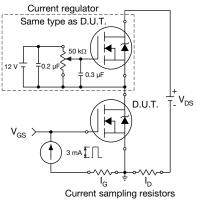
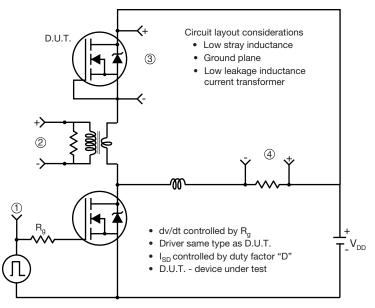


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



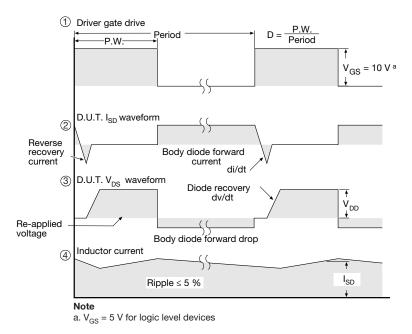
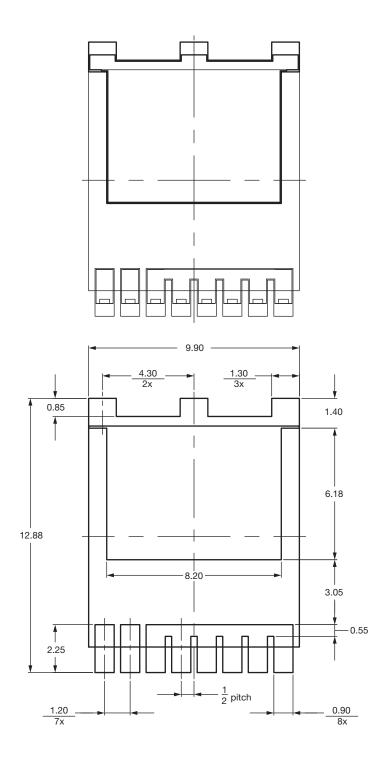


Fig. 19 - For N-Channel

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Vishay Siliconix

Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



Note

• Dimensions in mm

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DWG: 3013

Revision: 26-Dec-2022 1 Document Number: 92489



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